

The effect of temperature on the calculated bulk vacancy formation energy in Al and Cu

C van der Walt , HC Swart and JJ Terblans

Department of Physics, University of the Free State, PO Box 339, Bloemfontein, ZA-9300, South Africa

E-mail address: terblansjj@ufs.ac.za

Abstract. The bulk vacancy formation energies (E_v) were calculated for Al and Cu single crystals with a molecular dynamics simulation that made use of the Sutton-Chen many-body potential. The vacancy formation energies for single crystals with the surface orientations of (111), (100) and (110) were calculated at temperatures ranging from 0 K to below the melting temperatures. The values obtained for vacancy formation energies at 0 K compared well to values obtained from literature and exhibited E_v values that reflect the respective surface stabilities. The (111) surface has the greatest stability and had the highest bulk vacancy formation energy, followed by the (100) surface, and finally the (110) surface showed the greatest instability and had the lowest bulk vacancy formation energy. The E_v values at higher temperatures show surface instability, particularly in Cu(110), where it is caused by an adatom layer that forms on the surface at temperatures well below melting point. A general trend of a decrease of vacancy formation energy was observed for increasing temperature.

1. Introduction

The vacancy formation energy is an important factor in atomic transport, and is of fundamental importance in diffusion kinetics. The vacancy formation energy, (E_v) has been shown to be dependent on surface orientation in both Al and Cu. [1,2] What has not yet been extensively studied is the effect of temperature on these vacancy formation energies, but with the use of density functional theory (DFT) it has been shown for Pt, Pd and Mo that the vacancy formation energy increases with temperature. [3]

Perfect crystals of Al and Cu were simulated with the use of an embedded atom potential developed by Sutton and Chen. [4] The crystals were simulated with surface orientations of (100), (110) and (111) at a range of temperatures. The Sutton–Chen potential (U_i) is an embedded atom potential with a many-body term that uses particle densities in FCC metals. The total energy of the simulated crystal (U) can be calculated by using

$$U = \sum_i U_i = \varepsilon \sum_i \left[\frac{1}{2} \sum_{i \neq j} \frac{1}{2} V(r_{ij}) - c \sqrt{\rho_i} \right] \quad (1)$$

Where ε is an energy parameter and c is a dimensionless scaling parameter. V is the pairwise repulsive potential and ρ_i is a density like term;

$$V(r_{ij}) = \left(\frac{a}{r_{ij}} \right)^n \quad (2)$$

$$\rho_i = \sum_{i \neq j} \phi(r_{ij}) = \sum_{i \neq j} \left(\frac{a}{r_{ij}} \right)^m \quad (3)$$

with r_{ij} the distance between atoms i and j , a is the lattice constant, n a positive integer that determines the repulsive potential and m is a positive integer that determines the range of the repulsive potential such that $n > m$. The parameters that were used for Al and Cu are those published by Sutton and Chen, which are listed in Table 1.

Table 1. The Sutton–Chen parameters for Al and Cu. [4]

Element	ε (eV)	a (Å)	c	n	m
Al	3.3147×10^{-2}	4.05	16.399	7	6
Cu	1.2382×10^{-2}	3.61	39.432	9	6

2. Calculations

Using the Schottky mechanism to describe the vacancy formation energy (E_v) that has been defined as finding the difference between the energy needed to remove an atom from inside the crystal volume and the energy obtained from adding an atom to the crystal surface. The vacancy formation energy (E_v) can be calculated with: [1,2,5]

$$E_v = E_{coh}^{(Bulk)} - E_{coh}^{(surface)} \quad (4)$$

$E_{coh}^{(Bulk)}$ is the cohesive binding energy for an atom in the bulk of a crystal and $E_{coh}^{(surface)}$ is the binding energy for the added atom (adatom) on the surface. To calculate the bulk vacancy formation energy (E_v), the total energy (U^{total}) for a perfect crystal the Sutton–Chen potential needs to be calculated. Single crystals of Al and Cu with different surface orientations were simulated as shown in figure 1. Each of the crystals, Al(100), Al(110), Al(111), Cu(100), Cu(110) and Cu (111) with 1944 atoms each was simulated. The crystals each had six layers of 18×18 atoms. This was to account for the effects of using periodic boundaries, while taking into account processing limitations and still simulating a system large enough to simulate bulk. The corresponding vacancy formation energies were calculated at temperatures ranging from 0 K at 100 K intervals to a temperature below their respective melting points.

Using the Sutton–Chen empirical many-body potential, the interactive forces between the atoms were calculated and the crystal structures were allowed to relax for 20 000 steps and the total energy (U^{total}) for the relaxed crystal was then obtained. A vacancy was then created by removing the centre atom to a distance of 1 m from the crystal surface to approximate infinity, where the interactive forces between the adatom and the surface become negligible. The total energy (U^{total}) of the crystal with a vacancy was then measured again. The difference between these two total crystal energies is the bulk cohesive binding energy $E_{coh}^{(Bulk)}$.

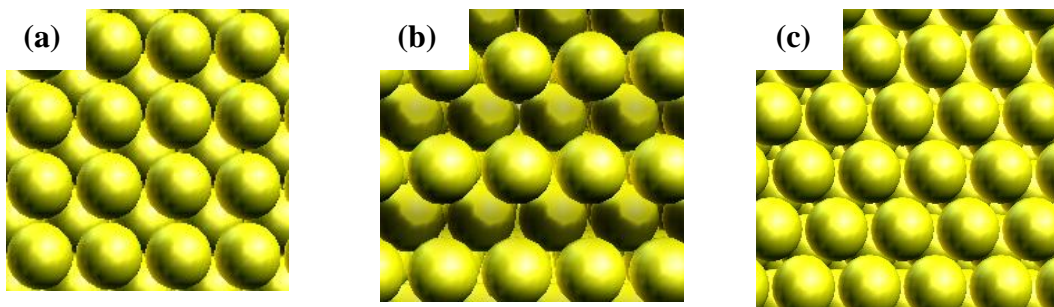


Figure 1. Schematics of the three different surface orientations of the bulk crystals: (100) in 1(a), (110) in 1(b) and (111) in 1(c).

To find the cohesive surface binding energy for the adatom $E_{coh}^{(surface)}$, the change in total energy (U^{total}) was calculated for the relaxed crystal with a vacancy in the centre, as an adatom was moved closer to the surface from infinity. This was done for all possible positions on surface to find the most preferred binding positions. Figure 2 shows the calculated potential energy curve as the adatom is moved closer to Cu(100), Cu(110) and Cu(111) surfaces.

Preferred binding sites were chosen as the points with the lowest maximum surface binding energy. Using likely bonding sites, the average surface binding energy for each crystal was determined for each of the various temperatures. The binding energies were measured five times over time to obtain a better average of the surface binding energy for each temperature.

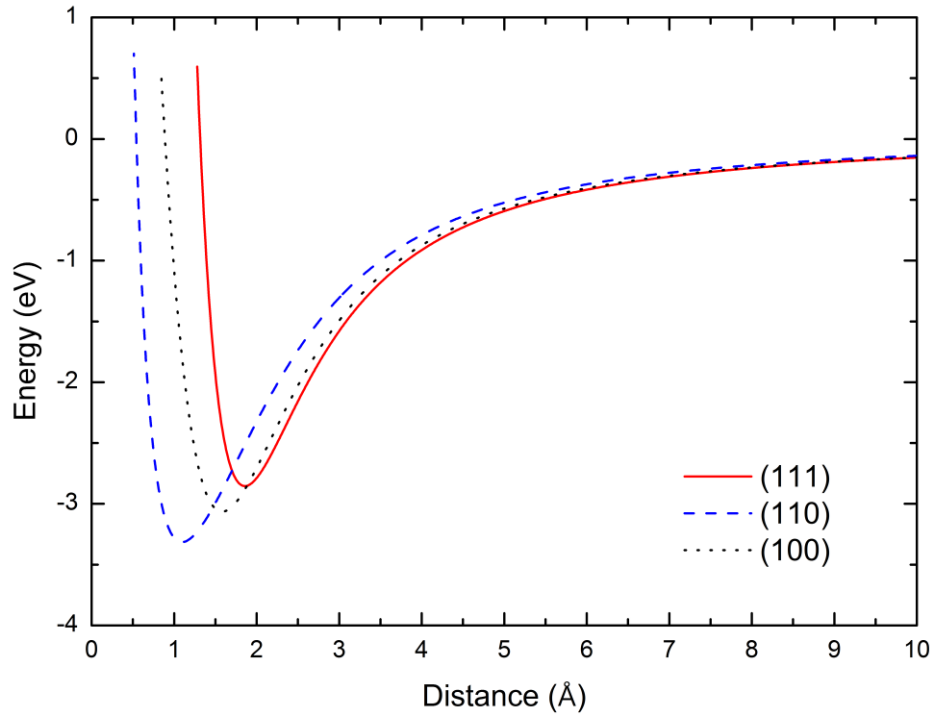


Figure 2. A potential energy curve of a single atom added to Cu(100), Cu(110) and Cu(111) orientated surfaces respectively.

3. Results And Discussions

As described in section 2, the binding energies for adatoms added onto Al(111), Al(100) and Al(110), and Cu(100), Cu(110) and Cu(111) surfaces were calculated. The values obtained for the maximum surface binding energies on each point of the surface was plotted in a contour plot for selected temperatures of Cu and is shown in figure 3. To find the best binding sites, the binding energy of preferred binding sites were averaged. The results for the calculated surface binding energies for Cu and Al at 0 K are summarized in table 2 and compared to values from literature. The values of 3.09 eV, 3.14 eV and 2.96 eV for Al(100), Al (110) and Al(111) respectively correspond very well with the values of 2.81 eV, 2.94 eV and 2.65 eV from the literature. [2] The values calculated the surface binding energies in low index Cu also compare very well (see table 2). [1]

From the cohesive surface binding energy for the adatom $E_{coh}^{(surface)}$ and the bulk cohesive binding energy $E_{coh}^{(Bulk)}$ the bulk vacancy formation energy (E_v) was calculated. The same process as described in section 2 was repeated for 0 K and the results of the bulk vacancy formation energy (E_v) was also tabulated in table 2, along with values from literature.

Table 2. Summary of the calculated surface binding energies and the calculated bulk vacancy formation energies compared results from literature.

Surface	Calculated E_v (eV/atom)	E_v from literature (eV/atom)	Calculated $E_{coh}^{(surface)}$ (eV/atom)	$E_{coh}^{(surface)}$ from literature (eV/atom)
Al(100)	0.72	0.50 ^[2]	3.09	2.81 ^[2]
Al(110)	0.66	0.37 ^[2]	3.14	2.94 ^[2]
Al(111)	0.83	0.66 ^[2]	2.96	2.65 ^[2]
Cu(100)	1.35	1.34 ^[1]	2.99	3.05 ^[1]
Cu(110)	1.07	1.07 ^[1]	3.22	3.32 ^[1]
Cu(111)	1.52	1.54 ^[1]	2.81	2.85 ^[1]

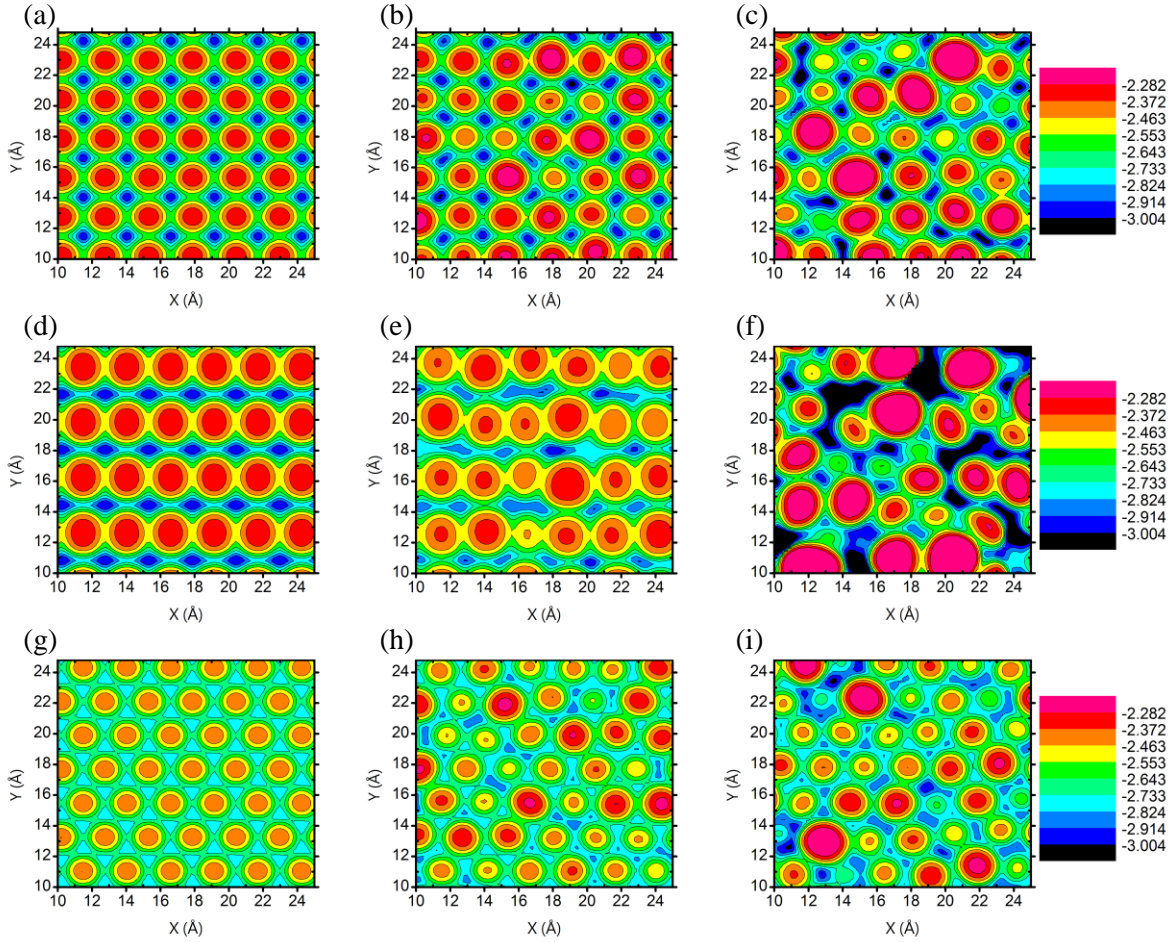


Figure 3. A contour plot was drawn showing the surface binding energies of the adatom on the Cu(100) surface at 0 K in 3(a), at 400 K in 3(b) and at 800 K 3(c). The corresponding binding energies measured for each point on the Cu(110) bulk crystal surface is shown in figure 3(d-f) and the plots of Cu(111) can be seen in figure 3(g-i).

The calculated E_v 's of 1.52 eV for Cu(111), 1.35eV for Cu(100) and 1.07 eV for Cu(110) correspond well to the literature values of 1.54 eV for Cu(111), 1.34eV for Cu(100) and 1.07 eV for Cu(110), and there is a good agreement between the calculated and literature values of the Al E_v 's.

The calculations were repeated for crystals at higher temperatures. The Cu crystals were simulated at temperatures ranging in 100 K steps from 0 K up to 1000 K. At high temperatures a large degree of surface disordering was observed, especially for the (110) orientation, which exhibited roughening and the formation of an adlayer as can be seen in figure 3(f). Previous work in literature with an embedded atom model simulating a Cu(110) surface also showed the formation of an adlayer at 900 K through a generation of vacancies, and surface premelting at 80 K below the simulated bulk melting point. [6] Another study used a semi-empirical potential based on the tight-binding method to study the thermal behaviour of low index copper surfaces [7] and it was found in Cu(110) that above 700 K an adlayer formed due to adatom/vacancy formation, which lead to roughening and premelting of the Cu(110) surface. The Cu (100) surface showed disordering above 800 K, whereas the Cu(111) surface was observed to be the most stable with an ordered surface observed for high temperatures. The bulk vacancy formation energies for Cu at various temperatures is shown in figure 4, and shows a general trend of decreasing vacancy formation energy with increasing temperature. Further the error also increases with increasing temperature, which would suggest that the crystal simulated may have been too small.

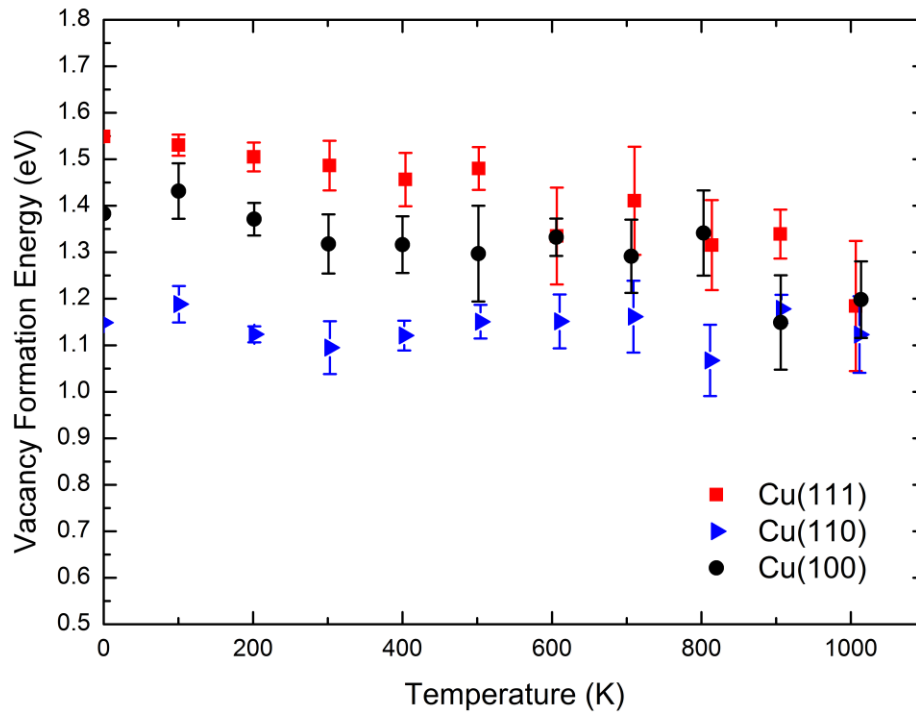


Figure 4. The vacancy formation energies (E_v) obtained for temperatures from 0 K to 1000K for Cu(100), Cu(110) and Cu(111) orientated surfaces.

The Sutton-Chen potential used to simulate the Al crystals showed melting of the surface at very low temperatures. Although the melting temperature of Al is found at 660 K, melting was found to occur at temperatures as low as 400 K. This underestimation of the melting temperature in Al has also

been observed before in thermodynamic studies of Al clusters and bulk simulations. [8–12] The Al surface was further found to premelt at temperatures below its melting temperature. [13] Al crystals were simulated for temperatures ranging up to 300 K and the resulting calculated vacancy formation energies (E_v) are shown in figure 5.

In both materials (Cu and Al), the bulk vacancy formation energy of the (111) surface crystals was larger than that of the (100) surface crystals, and that the bulk vacancy formation energy of the (100) surface crystals was found to be larger than that of the (110) surface crystals. The values calculated the vacancy formation energy of Schottky defects in low index Al and Cu at 0 K compare very well to values found in the literature. As the temperature increased the E_v 's tended to decrease, indicating a tendency for more vacancies to form at higher temperatures, which confirms observations.

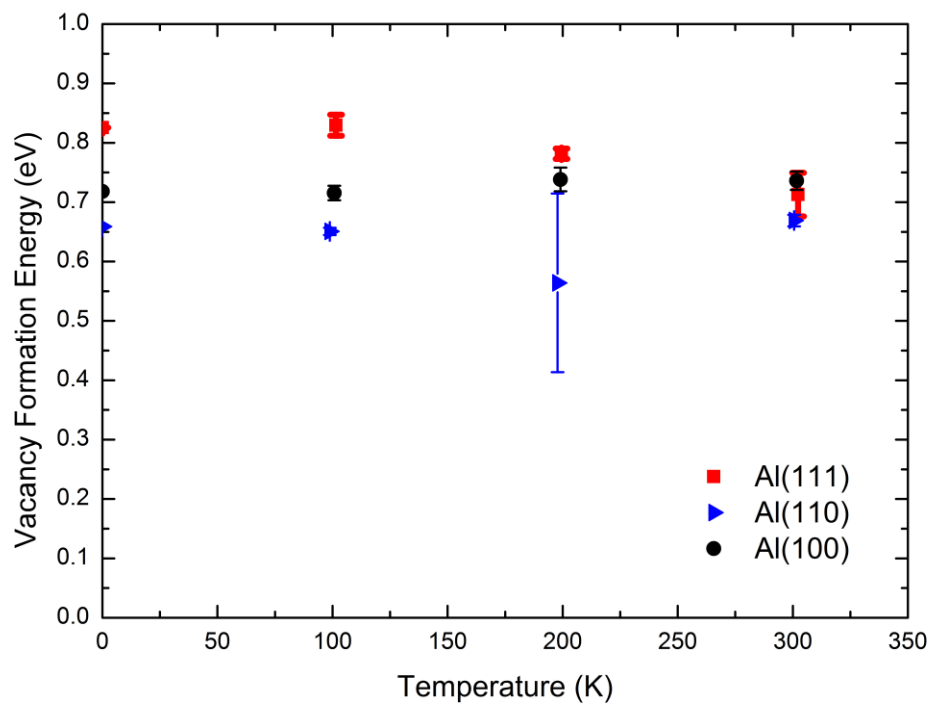


Figure 5. The effect of temperature on the vacancy formation energy in Al(111), Al(110) and Al(100).

4. Conclusion

Cu (100), (110) and (111), and Al (100), (110) and (111) bulk crystals were successfully simulated using the Sutton-Chen Potential. The bulk and surface cohesive energies for each of these crystals were measured at temperatures ranging from 0 K to 1000 K for Cu and 0 K to 300 K for Al. The Al melting temperature was underestimated by the Sutton-Chen potential and premelting in the surface was also observed. The Sutton-Chen also underestimates the melting temperature in Cu and surface effects such as a surface adlayer were observed. This effect was especially pronounced in Cu(110). Generally for both Al and Cu the vacancy formation energy was found to decrease with a temperature increase.

Acknowledgments

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5. References

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